

ABB <hr/>		Functional Testing Specification	
<i>Parts & Repair Services Louisville, KY</i>		LOU-GED-DS3800DDIB	
Test Procedure for a GE Daughter Board			
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PREPARED BY J. Wychulis		REVIEWED BY D. BUSH	REVIEWED BY
DATE 23DEC20		DATE 2/9/2021	QUALITY APPROVAL DATE

1. SCOPE

1.1 This is a functional testing procedure for a Card.

2. STANDARDS OF QUALITY

2.1 Refer to the current revision of the IPC-A-610 standard for workmanship standards.

3. APPLICABLE DOCUMENTS

3.1 The following document(s) shall form part of this specification to the extent specified herein.
Unless otherwise indicated, the latest issue shall apply.

3.1.1 Check board's electronic folder for more information

4. ENGINEERING REQUIREMENTS

4.1 Equipment Cleaning

4.1.1 Equipment should be clean and free of debris prior to applying power unless performing an initial check. Refer to site specific SRA's for cleaning guidelines.

4.2 Equipment Inspection

4.2.1 Equipment should be visually inspected for any defects prior to applying power. This inspection should include the following as a minimum:

4.2.1.1 Wires - broken, cracked, or loosely connected

4.2.1.2 Terminal strips / connectors - broken or cracked

4.2.1.3 Components - visually damaged

4.2.1.4 Capacitors - bloated or leaking

4.2.1.5 Solder joints - damaged or cold

4.2.1.6 Circuit board - burned or de-laminated

4.2.1.7 Printed wire runs / Traces - burned or damaged

5. EQUIPMENT REQUIRED

5.1 The following equipment is required to perform the process requirements. Equipment may be substituted provided that all accuracy's and test ratios are equivalent or better.

Qty	Reference #	Description
1		Fluke 87 DMM (or Equivalent)

6. Modifications/Upgrades

6.1 Fill out if applicable.

7. Testing Process

7.1 Setup

7.1.1 Just check the values listed below



Note:

7.2 Testing Procedure

7.2.1 JB1 – TP6 10K ohms

7.2.2 JB3 – TP1 10K

7.2.3 JB2 – JB3 VCAL pot 0-20k ohm check range

7.2.4 JB4 – TP2 10K ohms

7.2.5 JB5 – JB6 VMET pot 0 – 10k check range

7.2.6 R9 – ACOM 15K

7.2.7 JB7 – JB8 MVC pot 0 – 20K check range

7.2.8 JB9 – TP3 10K

7.2.9 JB10 – TP4 10K

7.2.10 JB10 – JB11 TIA pot 0 – 50K check range

7.2.11 JB11 – Acom TIA pot 0 – 50K check range

7.2.12 JB12 – TP5 10K

7.2.13 JB25 – ACOM 0 ohms

7.2.14 JB26 – ACOM 0 ohms

7.2.15 JB13 – JB14 IAM pot 0 – 10k ohms check range

7.2.16 JB14 – ACOM IAM pot 22k – 30k check range

7.2.17 JB15 – TP7 10K

7.2.18 JB16 – TP8 10K

7.2.19 JB17 – JB18 IFM pot 0 – 10K check range

7.2.20 JB18 – ACOM IFM pot 33k – 40K check range

7.2.21 JB19 – ACOM IAC pot 0 – 20K check range

7.2.22 JB20 – ACOM IFC pot 0 – 20K check range

7.2.23 Put J1 and J2 in the A position

7.2.24 JB21 – JB22 475 ohms

7.2.25 JB23-JB24 0 ohms

7.3 ***TEST COMPLETE ***

8. Notes

8.1 None at this time

9. Attachments

9.1 None at this time
